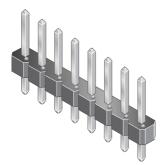
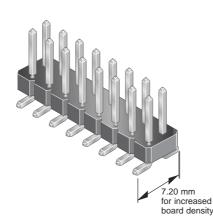
BergStik® Unshrouded Headers 2.54 mm











- High temperature plastic
- Selective plating



Technical Data

Physical

Housing: High temperature, black thermoplastic

Flammability rating: UL 94 V-0

Pin: Phosphor-bronze

Plating: Gold or tin-lead over 1.27 µm nickel

Electrical Performance

Current rating: 3 A continuous Insulation resistance: 5000 M Ω min. Dielectric withstanding voltage: 1500 V

Mechanical Performance

Pin retention to housing: 9 N min.

Operating Temperature Range

-65°C to +125°C

Packaging

Standard: Bags Optional: Tubes or

Tape-and-reel with pick-up cap (SMT pin style 01 only)

Reference Information

SI File no. E66906

File no. LR46923

Product drawing: By 5-digit base part number Product specification: BUS-12-114 Tape and Reel packaging data: TA 840 Specifications subject to change without notice.

Mating Data

Page ■ Dubox[™] Crimp-to-wire contacts 18 ■ Dubox[™] Crimp-to-wire housings 20

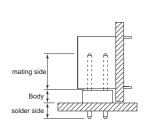
Dubox[™] Vertical receptacles 24 Dubox[™] Low profile vertical receptacles 26, 28

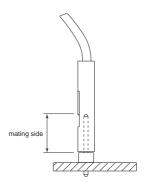
■ Dubox[™] Horizontal receptacles 30 ■ Quickie[™] IDC receptacles 32 ■ Dubox[™] Shunts 36

Processing Information

Compatible with wave, vapor-phase, and IR reflow soldering processes

Recommended IR profile TA 842 for SMT

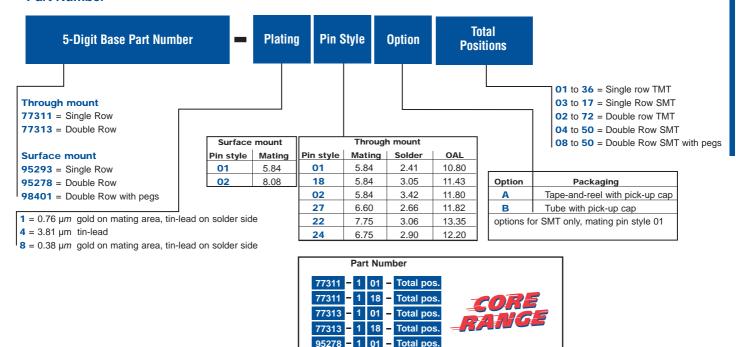


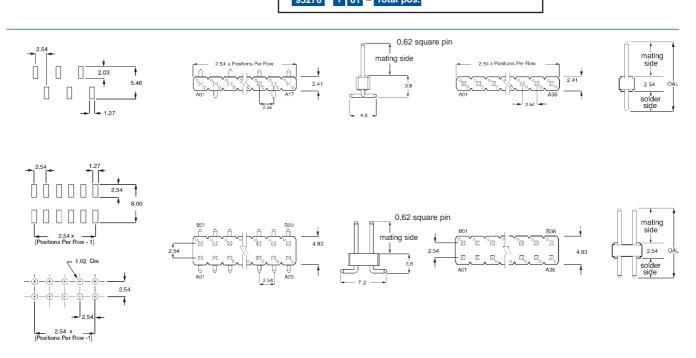


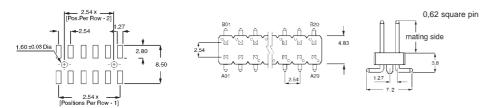












Recommended PCB Layout



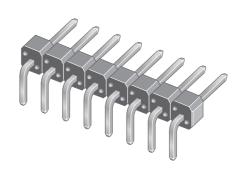
BergStik® Unshrouded Headers 2.54 mm





- High temperature plastic
- Selective plating







Technical Data

Physical

Housing: High temperature, black thermoplastic

Flammability rating: UL 94 V-0

Pin: Phosphor-bronze

Plating: Gold or tin-lead over 1.27 μm nickel

Electrical Performance

Current rating: 3 A continuous Insulation resistance: 5000 M Ω min. Dielectric withstanding voltage: 1500 V

Mechanical Performance

Pin retention to housing: 8.88 N min.

Operating Temperature Range

-65°C to +125°C

Packaging

Bags

Reference Information

File no. E66906

6 File no. LR46923

Product drawing: By 5-digit base part number Product specification: BUS-12-114

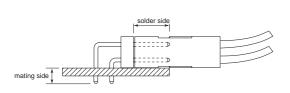
Specifications subject to change without notice.

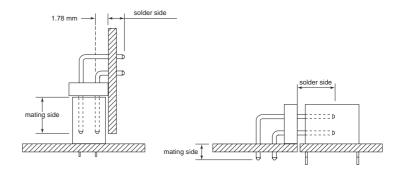
Mating Data

nating Data	Page
Dubox [™] Crimp-to-wire contacts	18
Dubox [™] Crimp-to-wire housings	20
■ Dubox [™] Vertical receptacles	24
■ Dubox [™] Low profile vertical receptacles	26, 28
Dubox [™] Horizontal receptacles	30
Quickie™ IDC receptacles	32
Dubox™ Shunts	36

Processing Information

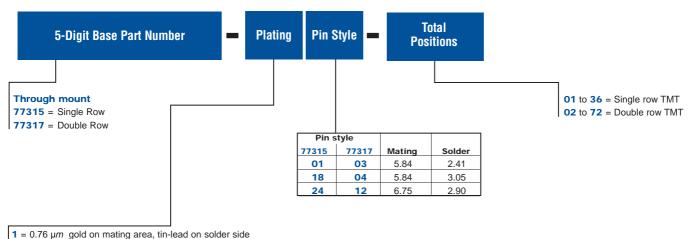
Compatible with wave, vapor-phase, and IR reflow soldering processes



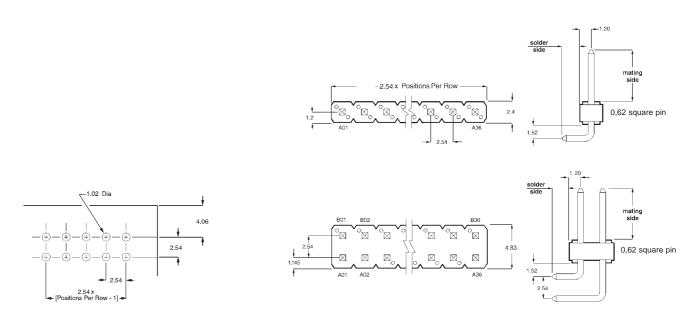








- $4 = 3.81 \ \mu m \ \text{tin-lead}$
- $8 = 0.38 \,\mu m$ gold on mating area, tin-lead on solder side

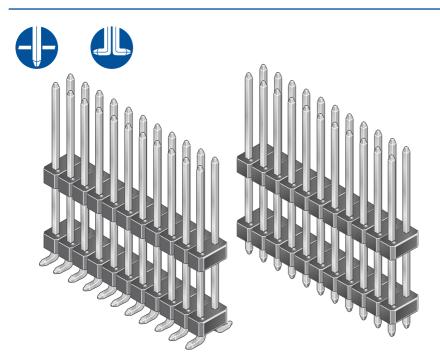


Recommended PCB Layout



BergStik® Unshrouded Stacking Headers 2.54 mm





- Wide variety of stack heights in 0.5 mm increments
- High temperature plastic
- Selective plating



Technical Data

Physical

Housing: High temperature, black thermoplastic

Flammability rating: UL 94 V-0

Pin: Phosphor-bronze

Plating: Gold or tin-lead over 1.27 µm nickel

Electrical Performance

Current rating: 3 A continuous Insulation resistance: 5000 $\mbox{M}\Omega$ min. Dielectric withstanding voltage: 1500 V

Mechanical Performance

Pin retention to housing: 9 N min.

Operating Temperature Range

-65°C to +125°C

Packaging

Standard: Bags

Reference Information

File no. E66906

File no. LR46923

Product drawing: By 5-digit base part number

Product specification: BUS-12-114

Specifications subject to change without notice.

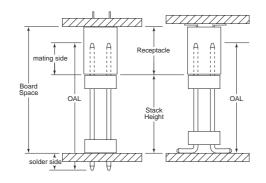
Mating Data

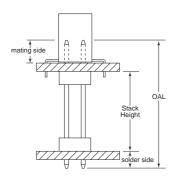
Page ■ Dubox[™] Vertical receptacles 24

■ Dubox[™] Low profile vertical receptacles 26, 28

Processing Information

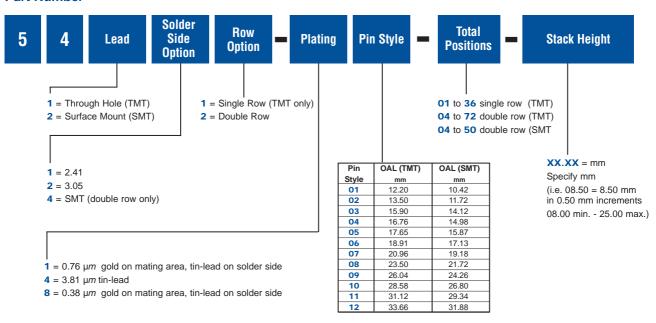
Compatible with wave, vapor-phase, and IR reflow soldering processes

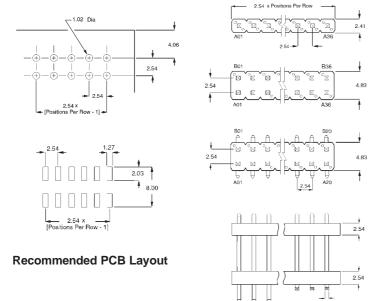












Step-by-Step Design

- 1. Determine desired board spacing (0.50 mm increments)
- Select Dubox[™] receptacle and calculate stack height Stack Height = Board Spacing – Receptacle Height
- Find the insertion depth from the chart below.
 Calculate max./min. OAL
 - OAL = Stack Height + solder side + Insertion Depth
- 4. Select the Pin Style with OAL between max. and min. values

	Dubox™ RECEPTACLES		
	Low Profile	Vertical	
Height	7.00	8.50	
Insertion Depth (max.)	6.10	6.10	
Insertion Depth (min.)	3.86	4.34	

Example:

- 1. Application requires a board spacing of 22.50
- Select the Dubox[™] Low Profile Receptacle with height of 7.00

The Header Stack Height is 22.50 - 7.00 = 15.50

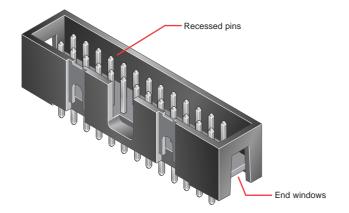
- 3. For standard board applications, the 3.05 solder side is selected
 - OAL (max.) = 15.50 + 3.05 + 6.10 = 24.65 OAL (min.) = 15.50 + 3.05 + 3.86 = 22.41
- 4. Select Pin Style 08 with OAL = 23.50
- 5. Part Number is 54122-108-72-1550



Quickie[™] Shrouded Low Profile Headers 2.54 mm







- Selective plating
- Recessed pins assure proper alignment and eliminate damage during mating
- End windows for latching with IDC receptacle



Technical Data

Physical

Housing: Glass filled, thermoplastic polyester, blue Flammability rating: UL 94 V-0

Pin: Phosphor-bronze

Plating: Gold or tin-lead over 1.27 µm nickel

Electrical Performance

Current rating: 3 A continuous Insulation resistance: 10,000 M Ω min. Dielectric withstanding voltage: 500 V min.

Mechanical Performance

Pin retention to housing: 20 N min.

Operating Temperature Range

-65°C to +125°C

Packaging

Tubes – Vertical Tubes – Right angle

Reference Information

SI File no. E66906

File no. LR46923

Product drawing: By 5-digit base partnumber Product specification: BUS-12-082

Specifications subject to change without notice.

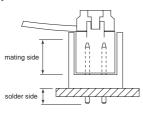
Mating Data

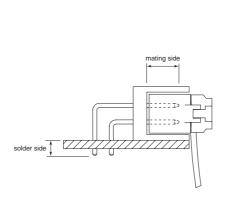
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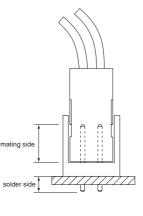
□ Dubox[™] Crimp-to-wire contacts
 □ Dubox[™] Crimp-to-wire housings
 □ Quickie[™] IDC receptacles
 32

Processing Information

Compatible with wave soldering processes

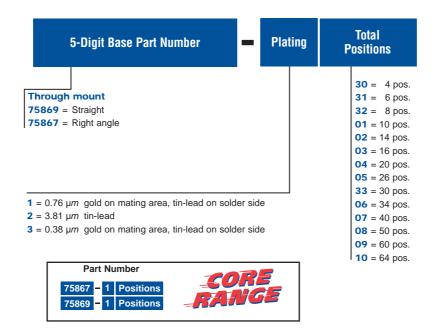






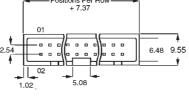


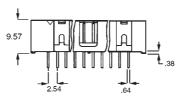


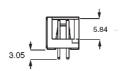


Vertical

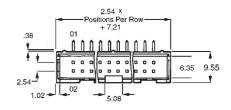
6.48 9.55

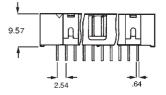


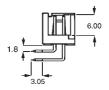




Right Angle







Dimensions in mm

-1.02 Dia

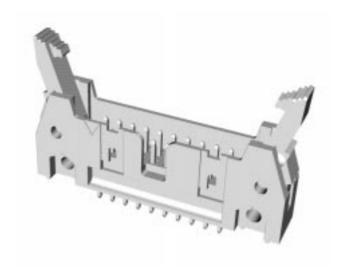
Recommended PCB Layout



Quickie[™] Shrouded Eject Latch Headers 2.54 mm







- Selective plating
- Recessed pins assure proper alignment and eliminate damage during mating



Technical Data

Physical

Housing: Glass filled, thermoplastic polyester, gray Flammability rating: UL 94 V-0

Pin: Phosphor-bronze

Plating: gold over 1.27 µm nickel

Electrical Performance

Current rating: 3 A continuous Insulation resistance: 10,000 M Ω min. Dielectric withstanding voltage: 1500 V

Mechanical Performance

Pin retention to housing: 20 N min.

Operating Temperature Range

-65°C to +125°C

Packaging

Bags – Vertical Bags – Right angle

Reference Information

File no. E66906

File no. LR46923

Product drawing: By 5-digit base part number

Product specification: BUS-12-082

Specifications subject to change without notice.

Mating Data

Page

32

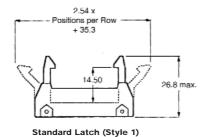
■ DuboxTM Crimp-to-wire contacts
 ■ DuboxTM Crimp-to-wire housings
 20

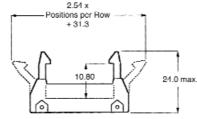
■ Quickie™ IDC receptacles

Processing Information

Compatible with wave soldering processes

Latching Styles

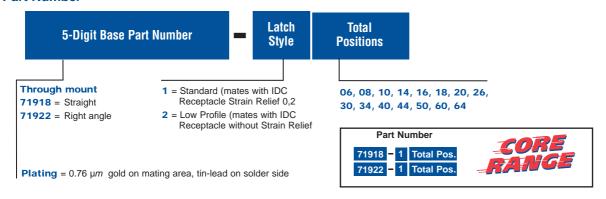


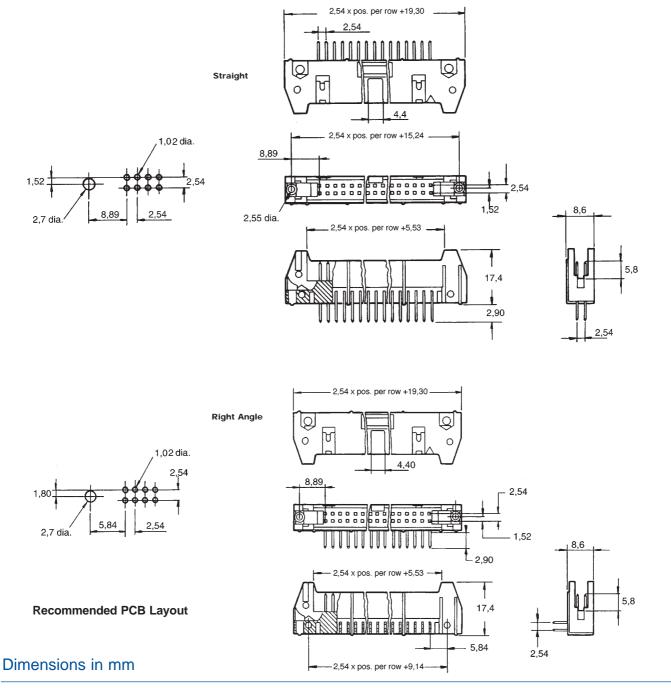


Low Profile Latch (Style 2)





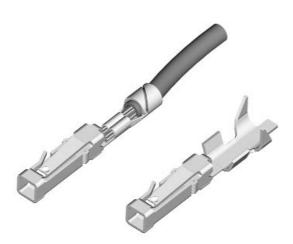






Dubox[™] Crimp-to-Wire Contacts 2.54 mm





- The DuboxTM contact has a prestressed, dual beam design to enable low insertion force.
- Mates with very short pins (5 mm)
- Universal crimp barrel accomodates wires from AWG 22-30
- Selective plating



Technical Data

Physical

Contact: phosphor bronze Plating: 0.76µm Gold over 1.27 µm nickel 5.0 µm tin-lead

Electrical Performance

Current rating: 3 A continuous Contact resistance after environmental test: 15 m Ω max. – Contact

Dielectric withstanding voltage: 1000 V rms

Mechanical Performance

Mating cycles (durability): 200 – Gold Insertion force gold finish contact: 1.3 N Withdrawal force (min) gold finish contact: 0.3 N

Operating Temperature Range

-65°C to +125°C

Packaging

Reels

Boxes - Loose piece

Reference Information

File no. E66906

File no. LR46923

Product drawing: By 5-digit base part number Product specification: BUS-12-055 – Contact Application specification: TA-317, TA-340 Specifications subject to change without notice.

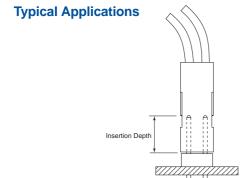
Mating Data

Page

- BergStik® unshrouded straight headers
- BergStik® unshrouded right angle headers 10
- Dubox[™] shrouded vert./ra. headers 22

Insertion Depth

- Discrete Wire: 3.56 mm min. to 5.59 mm max. [provides .381 mm wipe]
- Crimp-to-Wire Housing: 5.08 mm min. to 6.22 mm max.
 [provides .381 mm wipe in housing]



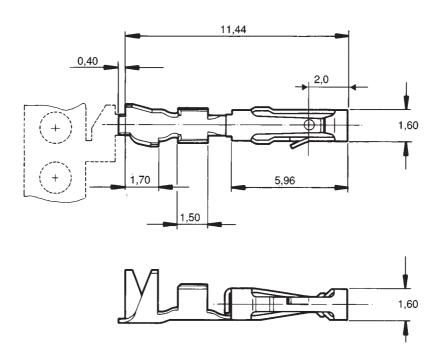




Wire size	insulation O.D.	Selective Plated	Tin-lead plated	Packaging
22-30	0.90 - 1.50	76347-301	76347-401	15.000/reel
22-30	0.90 - 1.50	76347-302•	76347-402•	15.000/reel
22-30	0.90 - 1.50	76347-303	76347-403	500/reel
20-22	1.10 - 1.60	76347-311	76347-411	15.000/reel
20-22	1.10 - 1.60	76347-312•	76347-412•	15.000/reel
Wire size	Pa	rt numbers / Con	tacts loose Piece	e Packaging

Part Number

76347 - 301 **CORE RANGE**



Contacts to be used with housing = 65239-xxx / 65240-xxx

Wire strip length = $3,00 \pm 0.25$ mm

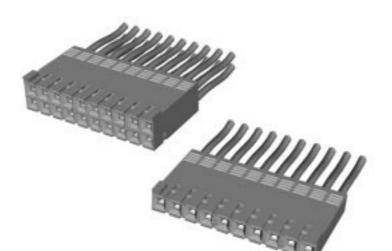
Mating pin size = 0,62 mm square

Mating pin recommended length = 5,00 mm min.



Dubox[™] Crimp-to-Wire Housings 2.54 mm





- For use with Dubox[™] crimp-to-wire contacts
- Stackable end-to-end
- Passive latching, anti-reverse and anti-miss-match when used with Dubox[™] shrouded headers
- Contacts removable for easy repairability



Technical Data

Physical

Housing: Glass filled thermoplastic polyester, blue

Flammability rating: UL 94 V-0

Electrical Performance

Insulation resistance: 1x 10^5 M Ω min. Dielectric withstanding voltage: 1000 V rms

Operating Temperature Range

-65°C to +125°C

Packaging

Bulk

Reference Information

SI File no. E66906

f: File no. LR46923

Product drawing: By 5-digit base part number Application specification: TA-317 / TA-340 Specifications subject to change without notice.

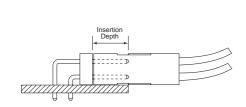
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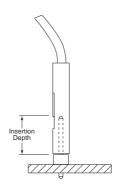
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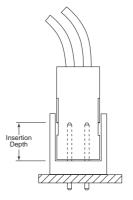
- BergStik® Unshrouded straight headers
- BergStik® Unshrouded right angle headers 10
- Dubox[™] Shrouded headers 22

Insertion Depth

■ 4.0 mm min. to 6.0 mm max.

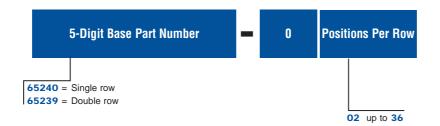




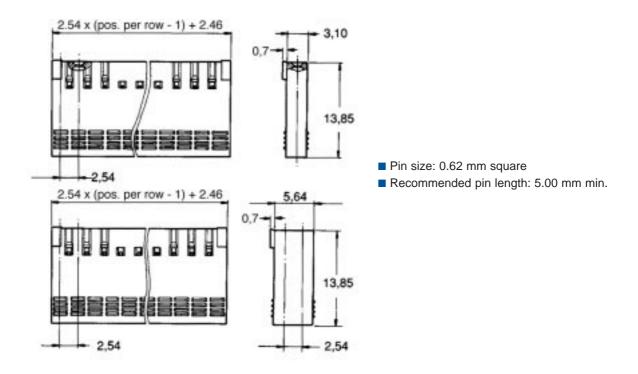












Dubox[™] Shrouded Headers 2.54 mm







- For use with DuboxTM crimp-to-wire housings
- Stackable end-to-end
- Passive latching, anti-reverse and anti-miss-match when used with Dubox[™] crimp-to-wire housings
- Selective plating



Technical Data

Physical

Housing: Glass filled thermoplastic

polyester, blue

Flammability rating: UL 94 V-0 Contact: Phosphor-bronze

Plating: Gold or tin-lead over 1.27 µm nickel

Electrical Performance

Current rating: 3 A continuous Insulation resistance: 1x $10^5~\text{M}\Omega$ min. Dielectric withstanding voltage: 1000 V rms

Mechanical Performance

Contact retention to housing: 20 N min.

Operating Temperature Range

-40°C to +125°C

Packaging

Tube

Reference Information

File no. E66906

File no. LR46923

Product drawing: By 5-digit base part number Application specification: TA-531

Specifications subject to change without notice.

Mating Data

Page

■ Dubox[™] Crimp-to-wire contacts

18 20

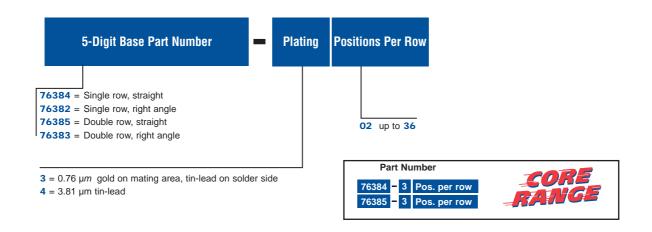
■ Dubox[™] Crimp-to-wire housings

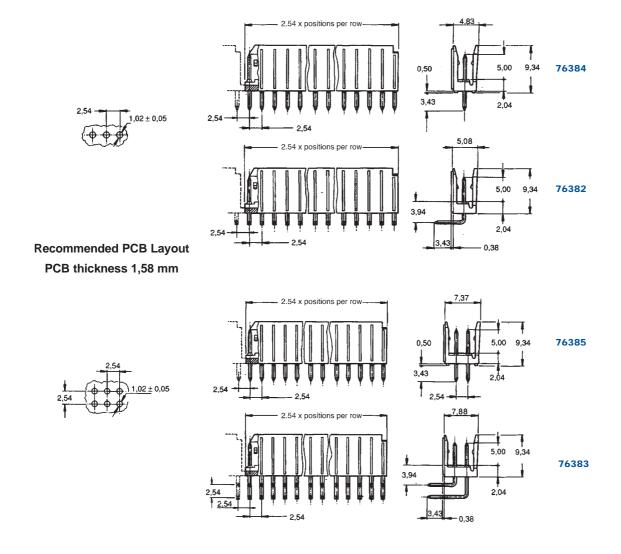
Processing Information

Compatible with wave soldering processes





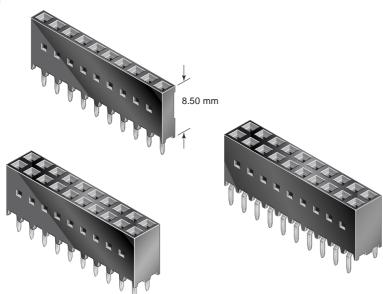




Dubox[™] Vertical Receptacles 2.54 mm







- The DuboxTM contact has a prestressed, dual beam design to enable low insertion force
- Selective plating



Technical Data

Physical

Housing: Glass filled thermoplastic

polyester, blue

Flammability rating: UL 94 V-0 Contact: Phosphor-bronze

Plating: Gold or tin-lead in accordance

with IEC 603-8

Electrical Performance

Current rating:

3 A dc max. per individual contact 2 A dc max. per contact for fully

energized connector

Insulation resistance: 1x 10^5 M Ω min. Contact resistance: 15 m Ω max. initial, 20 m Ω max. after environmental tests Dielectric withstanding voltage: 1000 V rms

Mechanical Performance

Mating cycles (durability): 200 Insertion force per gold contact: 1.50 N (150 gf) max. Withdrawal force per gold contact: 0.30 N (30 gf) min.

Operating Temperature Range

-65°C to +125°C

Packaging

Plastic boxes or tubes

Reference Information

File no. E66906

File no. LR46923

Product drawing: By 5-digit base part number Product specification: HE 13/14 and IEC 603-8 Specifications subject to change without notice.

Mating Data

Page 8

12

■ BergStik® Unshrouded straight headers

■ BergStik® Unshrouded right angle headers 10

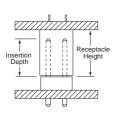
■ BergStik® Unshrouded stacking headers

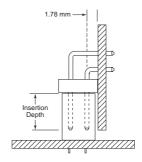
Insertion Depth

- Top Entry: 5.03 mm min. to 6.81 mm max. [provides .381 mm wipe]
- Bottom Entry: 6.25 mm min. [provides .381 mm wipe] plus board thickness

Processing Information

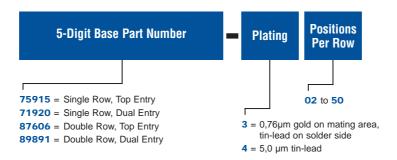
Compatible with wave soldering processes

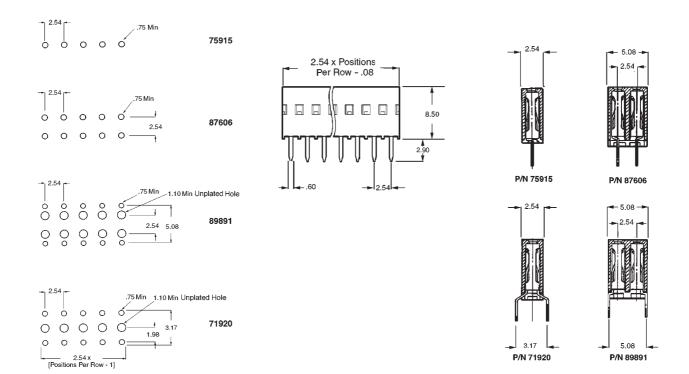












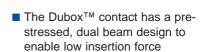
Recommended PCB Layout



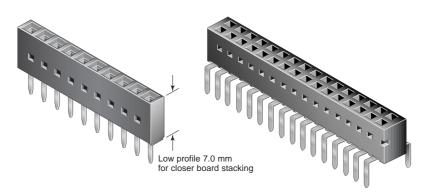
Dubox[™] Low Profile Vertical Receptacles 2.54 mm







■ Selective plating





Technical Data

Physical

Housing: Glass filled thermoplastic Flammability rating: UL 94 V-0 Contact: Phosphor-bronze

Plating: Gold or tin-lead over 1.27 µm nickel

Electrical Performance

Current rating:

3 A dc max. per individual contact 2 A dc max. per contact for fully energized connector

Insulation resistance: 1x $10^5~M\Omega$ min. Contact resistance: 15 m Ω max. initial, 20 m Ω max. after environmental tests Dielectric withstanding voltage: 1000 V rms

Mechanical Performance

Mating cycles (durability): 200 Insertion force per gold contact: 1.50 N (150 gf) avg. Withdrawal force per gold contact: 0.30 N (30 gf) min.

Operating Temperature Range

-65°C to +125°C

Packaging

Plastic boxes or tubes

Reference Information

SI File no. E66906

File no. LR46923

Product drawing: By 5-digit base part number Product specification: BUS-12-055

Specifications subject to change without notice.

Mating Data

Page

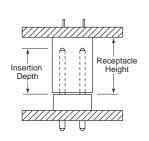
- BergStik® Unshrouded straight headers
- BergStik® Unshrouded right angle headers 10
- BergStik® Unshrouded stacking headers 12

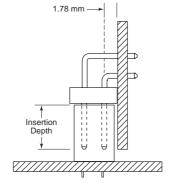
Insertion Depth

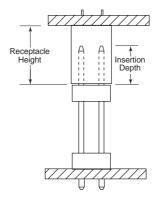
- Top Entry: 3.86 mm min. to 6.10 mm max. [provides .381 mm wipe]
- Bottom Entry: 5.08 mm min.[provides .381 mm wipe] plus board thickness

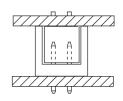
Processing Information

Compatible with wave soldering processes



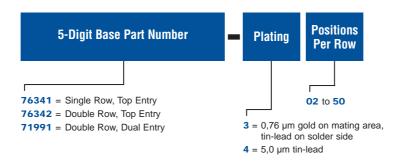








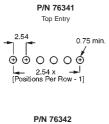


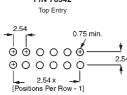


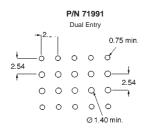


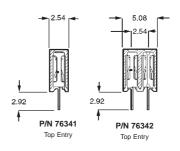
7.0

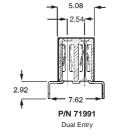
7.0









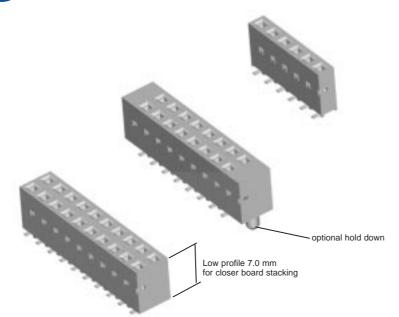


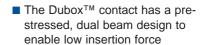
Recommended PCB Layout

Dubox[™] Low Profile Vertical Receptacles 2.54 mm









- Selective plating
- Floating solder tails self-center on circuit pads and assure coplanarity



Technical Data

Physical

Housing: High-temperature, grey thermoplastic

Flammability rating: UL 94 V-0 Contact: Phosphor-bronze

Plating: Gold or tin-lead over 1.27 µm nickel

Electrical Performance

Current rating: 3 A dc max. per individual contact

2 A dc max. per individual contact 2 A dc max. per contact for fully energized connector

Insulation resistance: $1x \ 10^5 \ M\Omega$ min. Contact resistance: $15 \ m\Omega$ max. initial, $20 \ m\Omega$ max. after environmental tests

Dielectric withstanding voltage: 1000 V rms

Mechanical Performance

Mating cycles (durability): 200 Insertion force per gold contact:

1.50 N (150 gf) avg.

Withdrawal force per gold contact: 0.30 N (30 gf) min.

Operating Temperature Range

-65°C to +125°C

Packaging

Tubes, Tape on Reel or plastic boxes

Reference Information

File no. E66906

File no. LR46923

Product drawing: By 5-digit base part number Product specification: BUS-12-055

Product specification: BUS-12-055
Tape and Reel packaging data: TA-856
Specifications subject to change without notice.

Mating Data

Page 8

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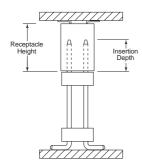
- BergStik® Unshrouded straight headers
- BergStik® Unshrouded right angle headers
- BergStik® Unshrouded stacking headers

Insertion Depth

- Top Entry: 3.86 mm min. to 6.10 mm max. [provides .381 mm wipe]
- Bottom Entry: 5.08 mm min. [provides .381 mm wipe] plus board thickness

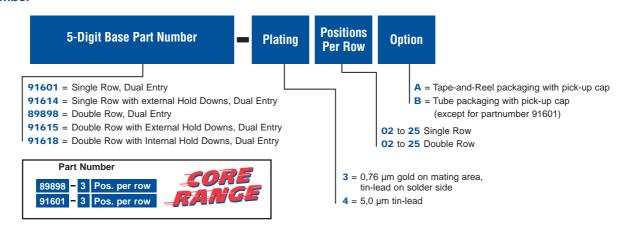
Processing Information

Compatible with wave, vapor-phase, and IR reflow soldering processes Recommended IR profile: TA-842

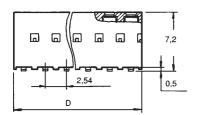






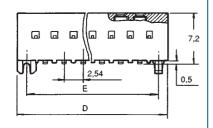






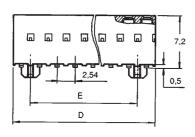
D = (no. of pos. per row x 2,54) - 0,08

External Hold Downs



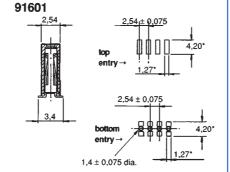
D = (no. of pos. per row x 2,54) + 5 E = (no. of pos. per row x 2,54) + 2,54

Internal Hold Downs

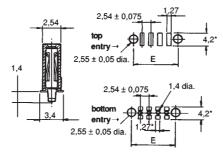


D = (no. of pos. per row x 2,54) - 0,08E = (no. of pos. per row x 2,54) - 5,00

Single Row + Pad lay-outs



91614

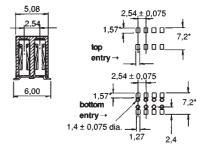


not available in single row

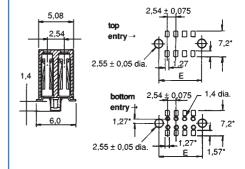
Note: All dimensions marked with * are minimum dimensions.

Double Row + Pad lay-outs

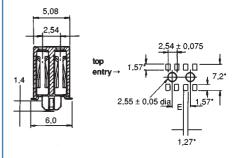
89898



91615



91618



Dubox[™] Horizontal Receptacles 2.54 mm









- The DuboxTM contact has a prestressed, dual beam design to enable low insertion force
- Selective plating
- Floating solder tails self-center on circuit pads and assure coplanarity



Technical Data

Physical

Housing: Blue thermoplastic – Through hole High temperature gray thermoplastic

Surface mount Flammability rating: UL 94 V-0

Contact: Phosphor-bronze

Plating: Gold or tin-lead over 1.27 µm nickel

Electrical Performance

Current rating:
3 A dc max. per individual contact
2 A dc max. per contact for fully
energized connector

Insulation resistance: 1x $10^5~M\Omega$ min. Contact resistance: 15 m Ω max. initial, 20 m Ω max. after environmental tests Dielectric withstanding voltage: 1000 V

Mechanical Performance

Mating cycles (durability): 200 Insertion force per gold contact: 1.50 N (150 gf) Withdrawal force per gold contact: 0.30 N (30 gf)

Operating Temperature Range

-65°C to +125°C

Packaging

Standard: Tubes Optional: Tape-and-reel

Reference Information

File no. E66906
File no. LR46923

Product drawing: 71607, 71609, 89882, 89883 Product specification: HE 13/14 and IEC 603-8 Application specification: TA-842 for SMT Tape and Reel packaging data: TA 840 Specifications subject to change without notice.

Mating Data

Page 8

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■ BergStik® Unshrouded straight headers

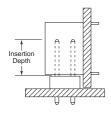
■ BergStik® Unshrouded right angle headers

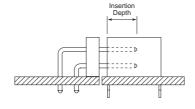
Insertion Depth

■ 5.00 mm min. to 7.50 mm max. [provides .381 mm wipe]

Processing Information

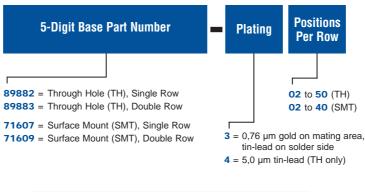
Compatible with wave, vapor-phase, and IR reflow soldering processes – Surface mount



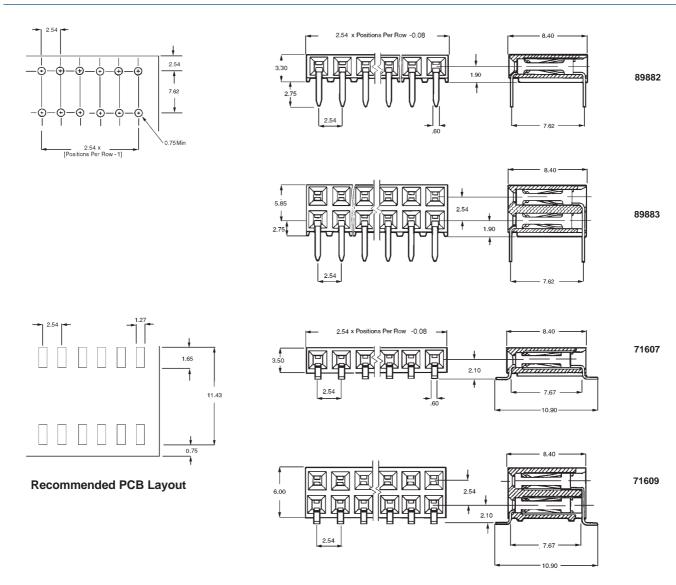








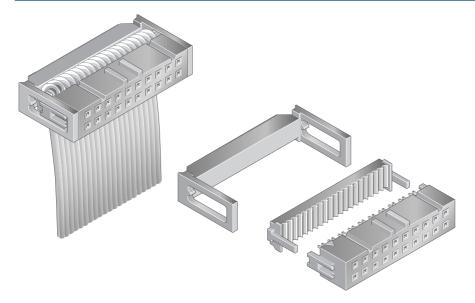






Quickie™ IDC Receptacles 2.54 mm





 Single-piece design provides one of the lowest applied costs in the industry



IDC Receptacles

Technical Data

Physical

Housing: Gray thermoplastic Flammability rating: UL 94 V-0 Contact: Phosphor-bronze

Plating: 0.76 µm Gold over 1.27 µm nickel

Electrical Performance

Current rating: 1 A continuous Insulation resistance: $50,000~M\Omega$ min. Contact resistance: $15~m\Omega$ max. Dielectric withstanding voltage: 1000~V min. rms (sea level)

Mechanical Performance

Mating cycles (durability): 100

Operating Temperature

-65°C to +105°C

Packaging

Tubes

Reference Information

File no. E66906
File no. LR46923

1 lie 110. LIX-10323

Product drawing: By 5-digit base part number

Product specification: BUS-12-095

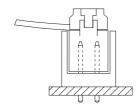
Specifications subject to change without notice.

Mating Data

Page 8

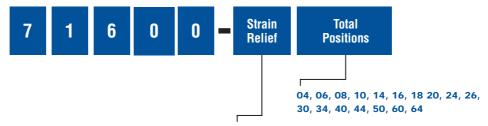
14

- BergStik® Unshrouded straight headers
- Quickie[™] Shrouded low profile headers
- Quickie[™] Shrouded eject latch headers 1



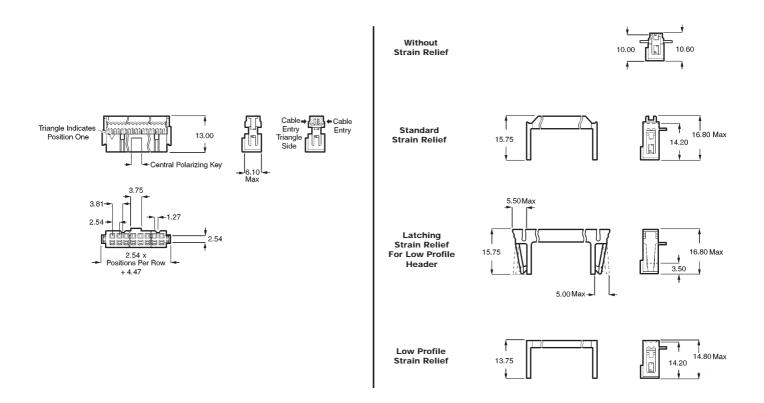






- **0** = Standard (Mates with Shrouded Eject Latch Header Latch 1)
- 1 = None (Mates with Shrouded Eject Latch Header Latch 2)
- 2 = Low Profile (Mates with Shrouded Eject Latch Header Latch 1)
- 6 = Latching (Mates with Low Profile Headers)

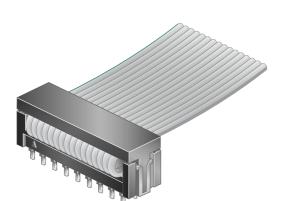




Quickie[™] IDC 2-Row PCB Connectors 2.54 mm







- Ideal for daisy chain applications
- Single-piece design provides one of the lowest applied costs in the industry



Technical Data

Physical

Housing: Blue thermoplastic Flammability rating: UL 94 V-0

Pin: Phosphor-bronze

Plating: Tin-lead over 1.27 µm nickel

Electrical Performance

Current rating: 1 A continuous Insulation resistance: 50,000 M Ω min. Contact resistance: 15 m Ω max.

Dielectric withstanding voltage: 1000 V min.

Operating Temperature

-65°C to +105°C

Packaging

Tubes

Reference Information

Al File no. E66906

File no. LR46923

Product drawing: By 5-digit base part number

Product specification: BUS-12-067

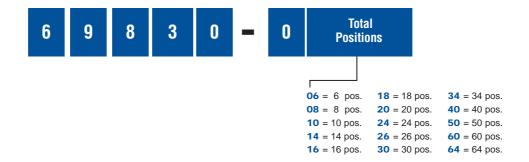
Specifications subject to change without notice.

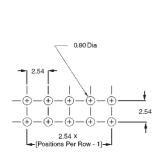
Processing Information

Compatible with wave and vapor-phase soldering processes – Low temperature

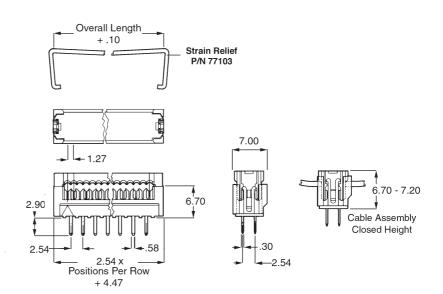








Recommended PCB Layout





- Dual-beam contacts for added reliability
- Slotted cut-out in low profile housing simplifies electrical testing
- Side-by-side and end-to-end stackable







Technical Data

Physical

Housing:

Glass filled thermoplastic polyester Blue or black

Flammability rating: UL 94 V-0 Pin: Phosphor-bronze

Plating: Gold or tin-lead over

1.27 µm nickel

Electrical Performance

Current rating: 3 A max. per contact Insulation resistance: $1x \cdot 10^5 \text{ M}\Omega \text{ min.}$ Contact resistance: 15 m Ω max. initial, 20 m Ω max. after environmental tests Dielectric withstanding voltage: 800 V

Mechanical Performance

Mating cycles (durability): 50 - Gold 25 – Tin-lead

Insertion force:

3.0 N (300 gf) max. per gold contact 4.5 N (450 gf) max. per tin-lead contact

Withdrawal force:

1.5 N (150 gf) min. per gold contact 2.0 N (200 gf) min. per tin-lead contact

Operating Temperature

-65°C to +125°C

Packaging

Bulk

Reference Information

File no. E66906

File no. LR46923

Product drawing: By 5-digit base number

Mating Data

Page 8

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12

- BergStik® Unshrouded vertical headers
- BergStik® Unshrouded right angle headers
- BergStik® Unshrouded stacking headers

Insertion Depth

■ 4.85 mm min.[provides 3.81 mm wipe]





